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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PC357NJ0000F Series

Mini-flat Package, General Purpose Photocoupler



■ Description

PC357NJ0000F Series contains an IRED optically coupled to a phototransistor.

It is packaged in a 4-pin Mini-flat package.

Input-output isolation voltage(rms) is 3.75kV.

Collector-emitter voltage is 80V and CTR is 50% to 600% at input current of 5mA.

■ Features

1. 4-pin Mini-flat package
2. Double transfer mold package (Ideal for Flow Soldering)
3. High collector-emitter voltage (V_{CEO} : 80V)
4. Current transfer ratio (CTR) : MIN. 50% at $I_F=5mA$, $V_{CE}=5V$
5. Several CTR ranks available
6. High isolation voltage between input and output ($V_{iso(rms)}$: 3.75kV)
7. RoHS directive compliant

■ Agency approvals/Compliance

1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. **PC357**)
2. Package resin : UL flammability grade (94V-0)

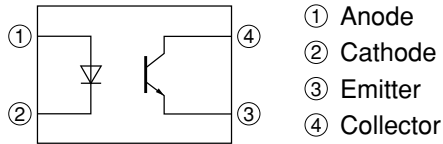
■ Applications

1. Hybrid substrates that require high density mounting
2. Programmable controllers

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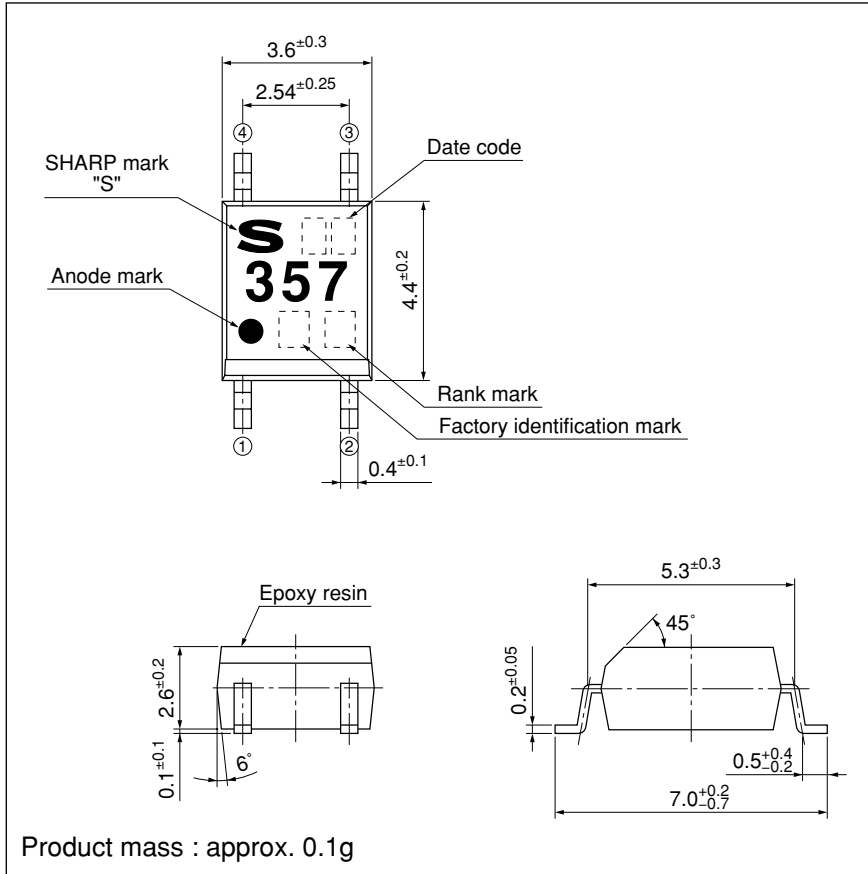
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Internal Connection Diagram



Outline Dimensions

(Unit : mm)






Plating material : SnCu (Cu : TYP. 2%)

Date code (2 digit)

1st digit				2nd digit	
Year of production				Month of production	
A.D.	Mark	A.D	Mark	Month	Mark
1990	A	2002	P	January	1
1991	B	2003	R	February	2
1992	C	2004	S	March	3
1993	D	2005	T	April	4
1994	E	2006	U	May	5
1995	F	2007	V	June	6
1996	H	2008	W	July	7
1997	J	2009	X	August	8
1998	K	2010	A	September	9
1999	L	2011	B	October	O
2000	M	2012	C	November	N
2001	N	∴	∴	December	D

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin
no mark	Japan
	
	Indonesia
	China

* This factory marking is for identification purpose only.
Please contact the local SHARP sales representative to see the actual status of the production

Rank mark

Refer to the Model Line-up table

■ Absolute Maximum Ratings (T_a=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	50	mA
	*1 Peak forward current	I _{FM}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V _{CEO}	80	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	I _C	50	mA
	Collector power dissipation	P _C	150	mW
	Total power dissipation	P _{tot}	170	mW
	Operating temperature	T _{opr}	-30 to +100	°C
	Storage temperature	T _{stg}	-40 to +125	°C
	*2 Isolation voltage	V _{iso (rms)}	3.75	kV
	*3 Soldering temperature	T _{sol}	260	°C

*1 Pulse width ≤ 100μs, Duty ratio : 0.001

*2 40 to 60%RH, AC for 1 minute, f=60Hz

*3 For 10s

■ Electro-optical Characteristics (T_a=25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage	V _F	I _F =20mA	-	1.2	1.4	V	
	Reverse current	I _R	V _R =4V	-	-	10	μA	
	Terminal capacitance	C _t	V=0, f=1kHz	-	30	250	pF	
Output	Collector dark current	I _{CEO}	V _{CE} =50V, I _F =0	-	-	100	nA	
	Collector-emitter breakdown voltage	BV _{CEO}	I _C =0.1mA, I _F =0	80	-	-	V	
	Emitter-collector breakdown voltage	BV _{ECO}	I _E =10μA, I _F =0	6	-	-	V	
Transfer characteristics	Collector current	I _C	I _F =5mA, V _{CE} =5V	2.5	5	30	mA	
	Collector-emitter saturation voltage	V _{CE(sat)}	I _F =20mA, I _C =1mA	-	0.1	0.2	V	
	Isolation resistance	R _{ISO}	DC500V, 40 to 60%RH	5×10 ¹⁰	1×10 ¹¹	-	Ω	
	Floating capacitance	C _f	V=0, f=1MHz	-	0.6	1.0	pF	
	Response time	Rise time	t _r	V _{CE} =2V, I _C =2mA, R _L =100Ω	-	4	18	μs
		Fall time	t _f		-	3	18	μs

■ Model Line-up

Package	Taping		Rank mark	I _C [mA] (I _F =5mA, V _{CE} =5V, T _a =25°C)
	3 000pcs/reel	750pcs/reel		
Model No.	PC357NJ0000F	PC357NTJ000F	with or without	2.5 to 30.0
	PC357N1J000F	PC357N1TJ00F	A	4.0 to 8.0
	PC357N2J000F	PC357N2TJ00F	B	6.5 to 13.0
	PC357N3J000F	PC357N3TJ00F	C	10.0 to 20.0
	PC357N4J000F	PC357N4TJ00F	D	15.0 to 30.0
	PC357N5J000F	PC357N5TJ00F	A or B	4.0 to 13.0
	PC357N6J000F	PC357N6TJ00F	B or C	6.5 to 20.0
	PC357N7J000F	PC357N7TJ00F	C or D	10.0 to 30.0
	PC357N8J000F	PC357N8TJ00F	A, B or C	4.0 to 20.0
	PC357N9J000F	PC357N9TJ00F	B, C or D	6.5 to 30.0
	PC357N0J000F	PC357N0TJ00F	A, B, C or D	4.0 to 30.0

Please contact a local SHARP sales representative to inquire about production status.

Fig.1 Forward Current vs. Ambient Temperature

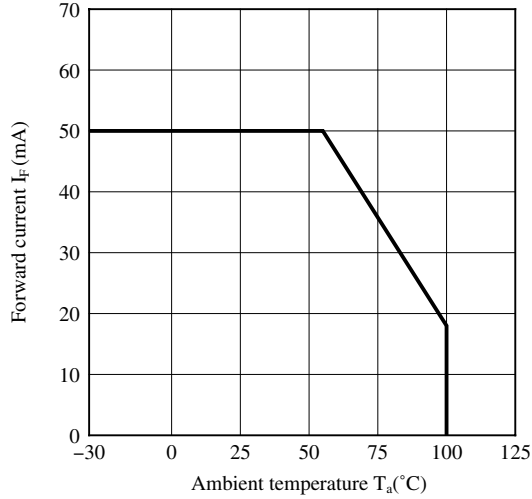


Fig.2 Diode Power Dissipation vs. Ambient Temperature

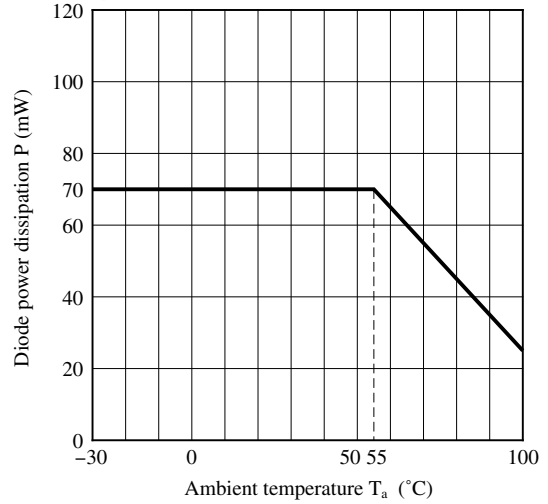


Fig.3 Collector Power Dissipation vs. Ambient Temperature

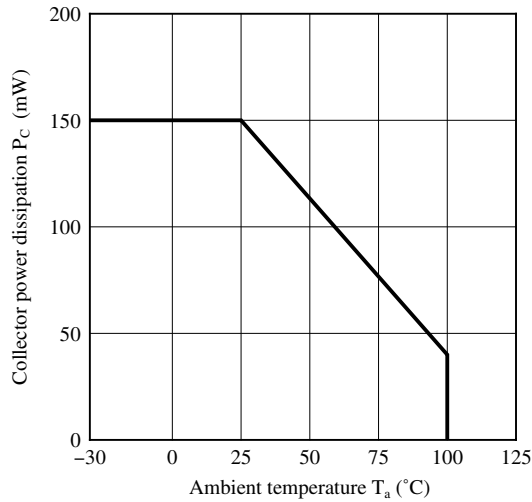


Fig.4 Total Power Dissipation vs. Ambient Temperature

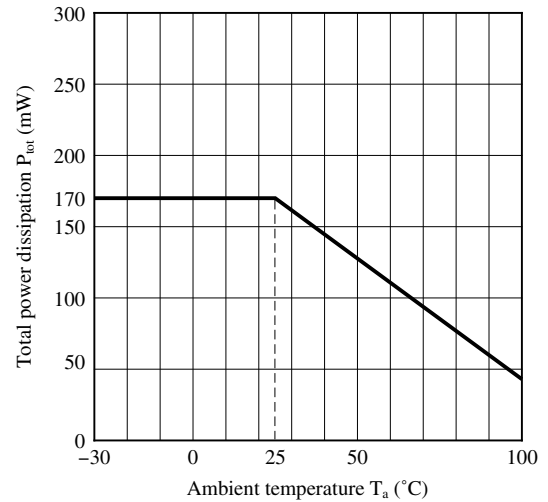


Fig.5 Peak Forward Current vs. Duty Ratio

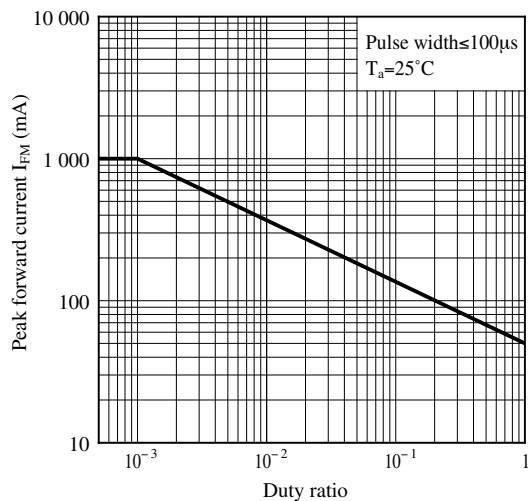


Fig.6 Forward Current vs. Forward Voltage

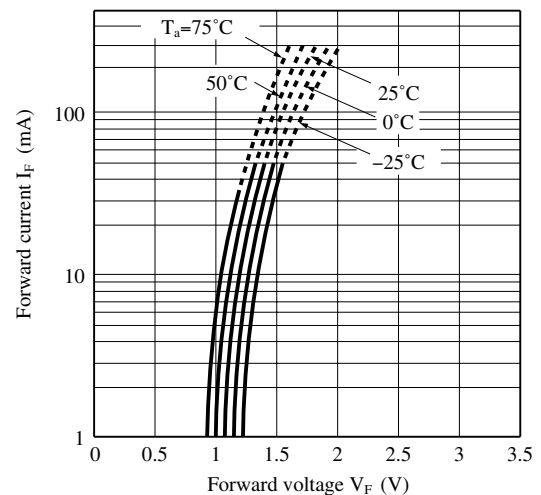


Fig.7 Current Transfer Ratio vs. Forward Current

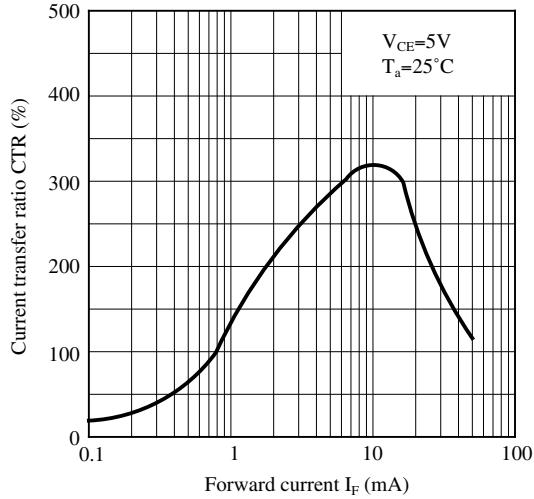


Fig.8 Collector Current vs. Collector-emitter Voltage

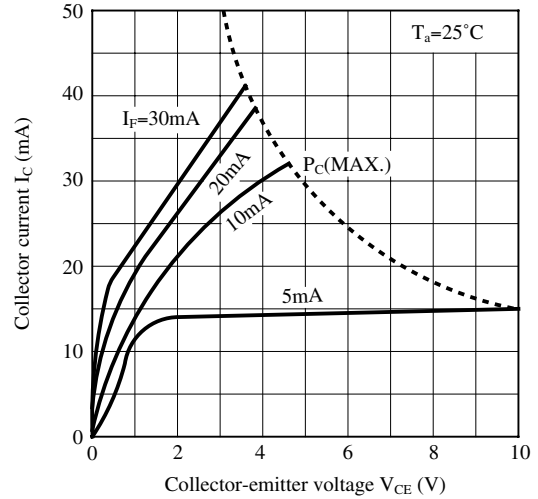


Fig.9 Relative Current Transfer Ratio vs. Ambient Temperature

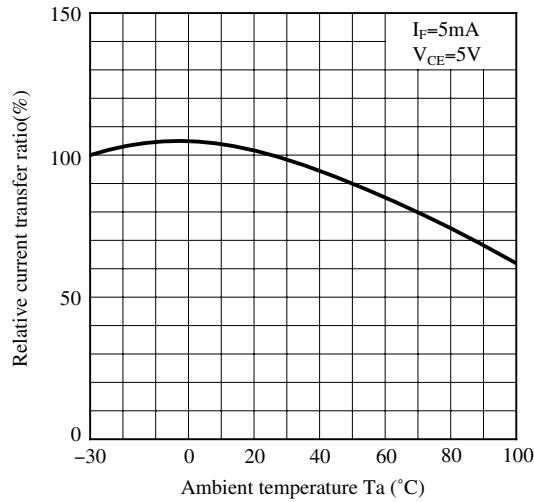


Fig.10 Collector - emitter Saturation Voltage vs. Ambient Temperature

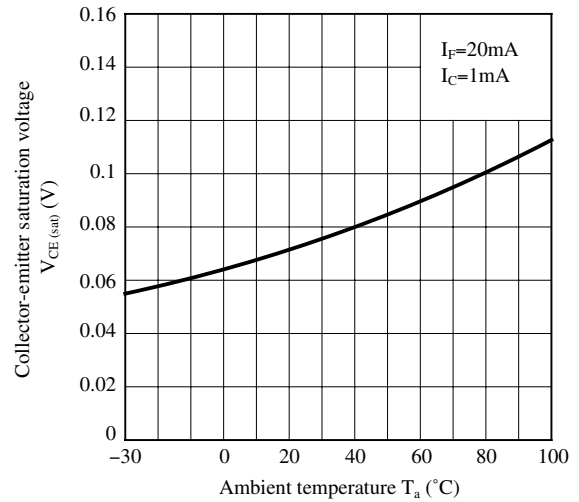


Fig.11 Collector Dark Current vs. Ambient Temperature

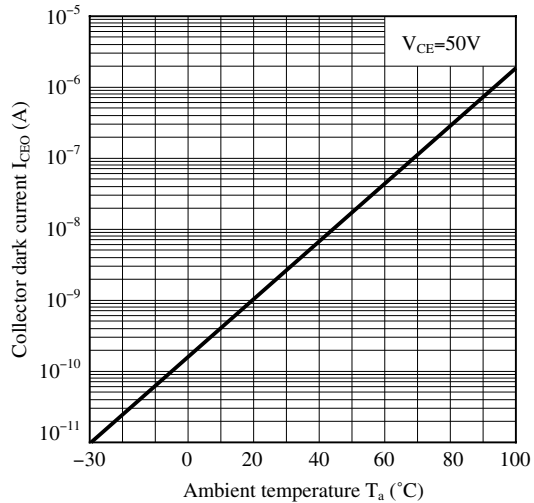


Fig.12 Response Time vs. Load Resistance

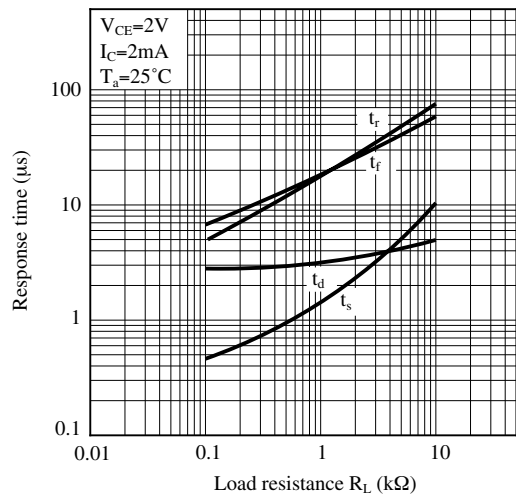
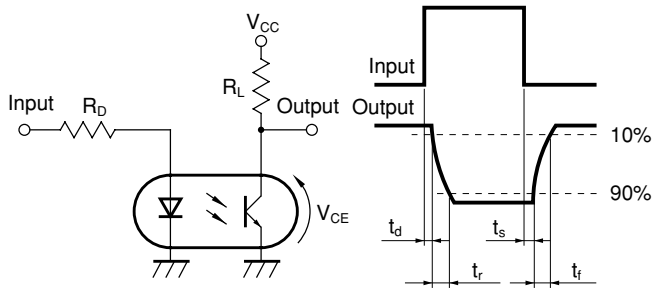
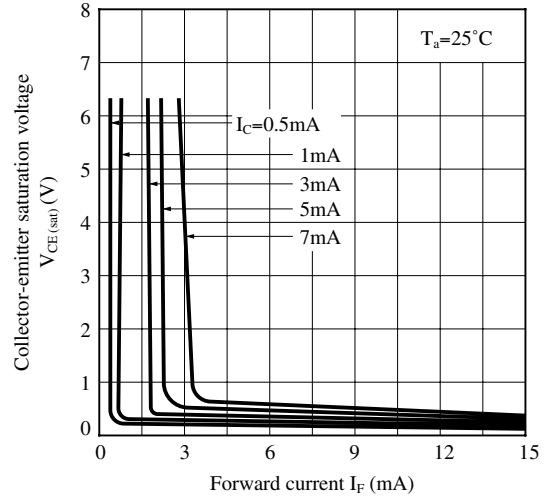


Fig.13 Test Circuit for Response Time



Please refer to the conditions in Fig.12

Fig.14 Collector-emitter Saturation Voltage vs. Forward Current



Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ Design Considerations

● Design guide

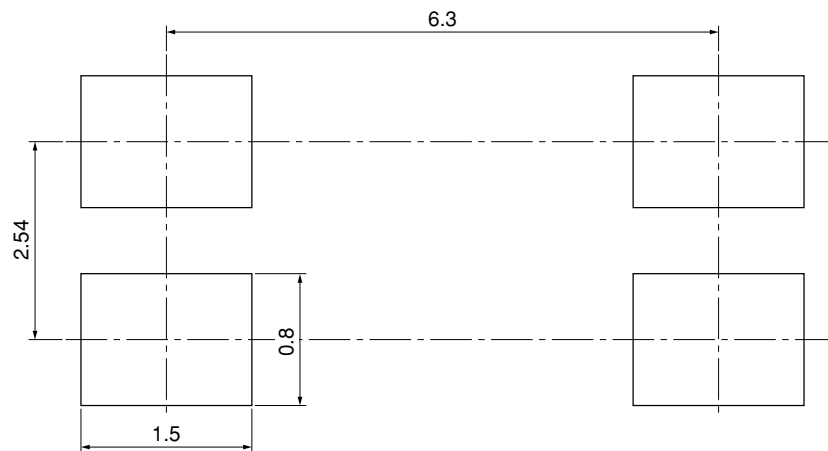
While operating at $I_F < 1.0\text{mA}$, CTR variation may increase.
Please make design considering this fact.

This product is not designed against irradiation and incorporates non-coherent IRED.

● Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.
In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

● Recommended Foot Print (reference)



(Unit : mm)

☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

■ Manufacturing Guidelines

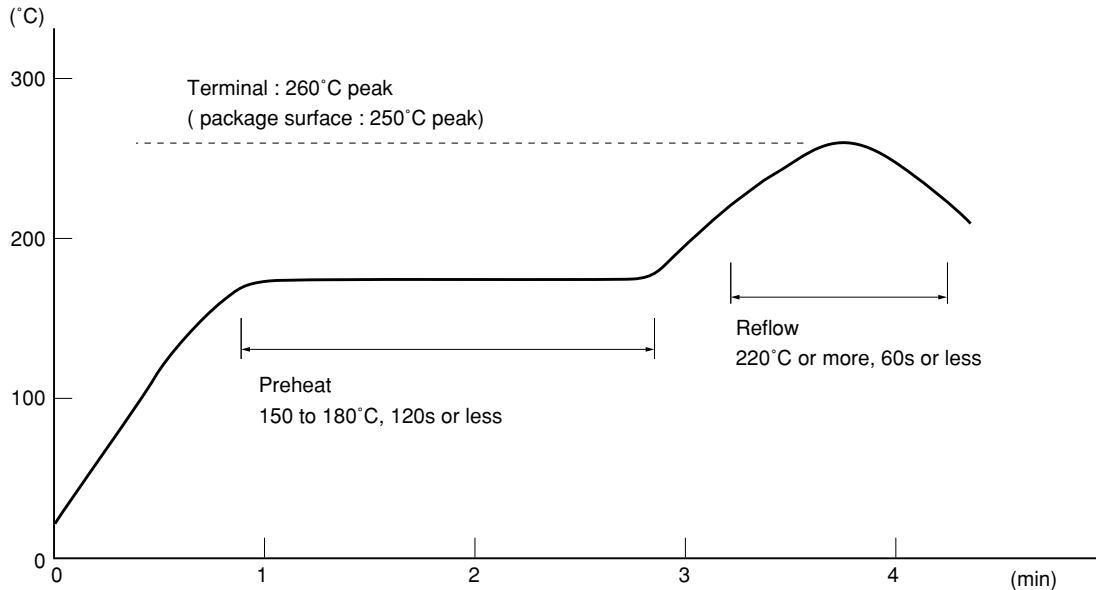
● Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please don't solder more than twice.



Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s.

Preheating is within the bounds of 100 to 150°C and 30 to 80s.

Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.

Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.

● Cleaning instructions**Solvent cleaning:**

Solvent temperature should be 45°C or below Immersion time should be 3 minutes or less

Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

● Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

■ **Package specification**

● **Tape and Reel package**

1. 3 000pcs/reel

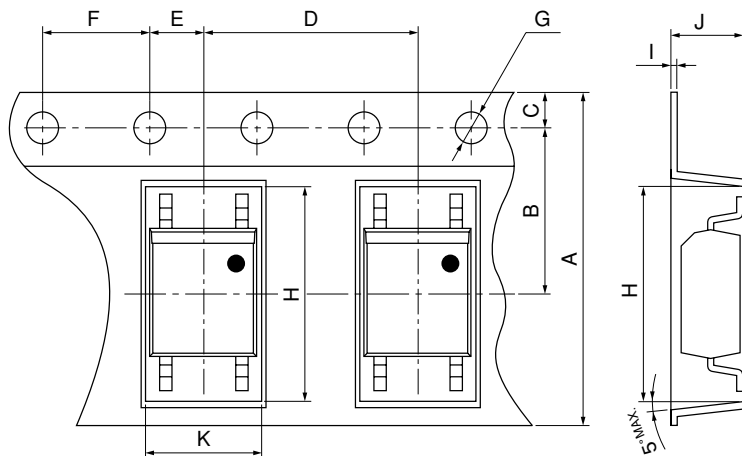
Package materials

Carrier tape : A-PET (with anti-static material)

Cover tape : PET (three layer system)

Reel : PS

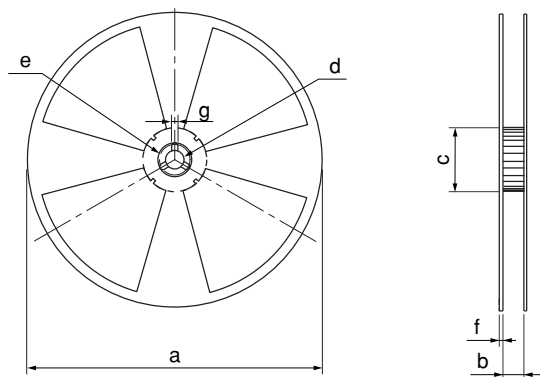
Carrier tape structure and Dimensions



Dimensions List (Unit : mm)

A	B	C	D	E	F	G
12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	φ1.5±0.1
H	I	J	K			
7.4±0.1	0.3±0.05	3.1±0.1	4.0±0.1			

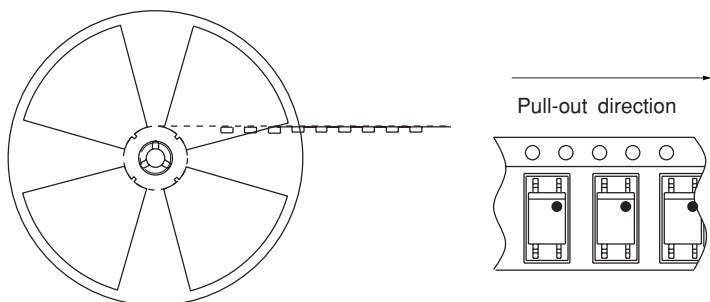
Reel structure and Dimensions



Dimensions List (Unit : mm)

a	b	c	d
370	13.5±1.5	80±1.0	13±0.5
e	f	g	
21±1.0	2.0±0.5	2.0±0.5	

Direction of product insertion



[Packing : 3 000pcs/reel]

2. 750pcs/reel

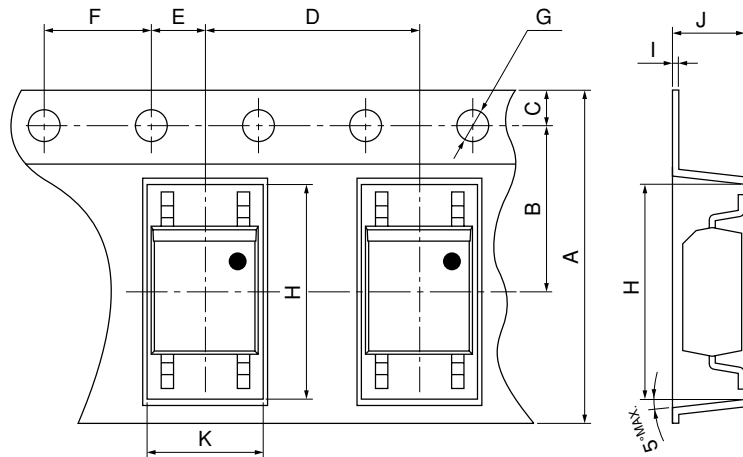
Package materials

Carrier tape : A-PET (with anti-static material)

Cover tape : PET (three layer system)

Reel : PS

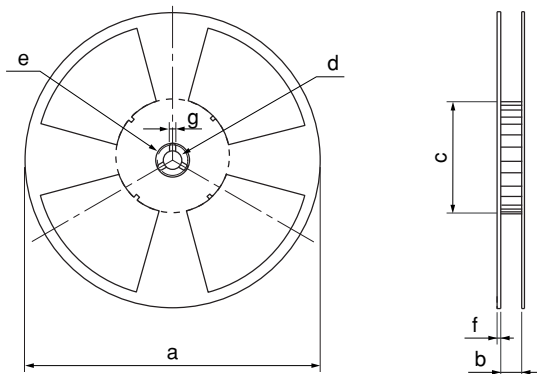
Carrier tape structure and Dimensions



Dimensions List (Unit : mm)

A	B	C	D	E	F	G
12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	φ1.5±0.1
H	I	J	K			
7.4±0.1	0.3±0.05	3.1±0.1	4.0±0.1			

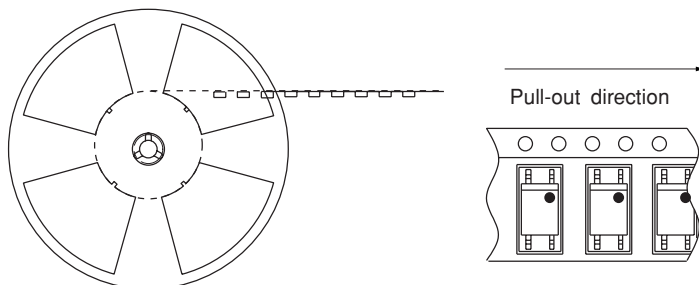
Reel structure and Dimensions



Dimensions List (Unit : mm)

a	b	c	d
180	13.5±1.5	80±1.0	13±0.5
e	f	g	
21±1.0	2.0±0.5	2.0±0.5	

Direction of product insertion



[Packing : 750pcs/reel]

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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- Personal computers
- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

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